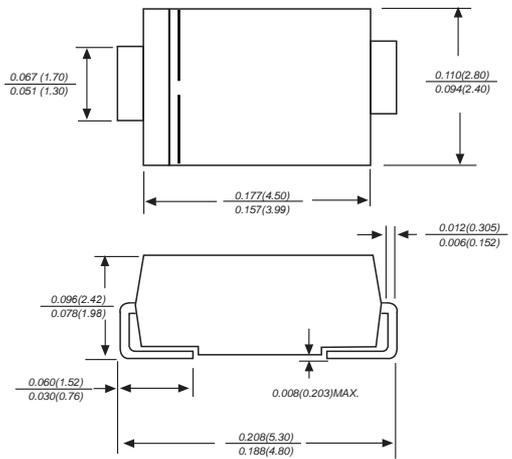


## Features

1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
2. For surface mounted applications
3. Metal silicon junction, majority carrier conduction
4. Low power loss, high efficiency
5. Built-in strain relief, ideal for automated placement
6. High forward surge current capability
7. High temperature soldering guaranteed:  
260°C/10 seconds at terminals

## DO-214AC/SMA



Dimensions in inches and (millimeters)

## Mechanical Data

**Case** : JEDEC DO-214AC/SMA Molded plastic body

**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity** : Polarity symbol marking on body

**Mounting Position** : Any

**Weight** : 0.002ounce, 0.07 grams

## Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave

60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SL32A	SL33A	SL34A	SL35A	SL36A	SL38A	SL310A	UNITS
		SL32A	SL33A	SL34A	SL35A	SL36A	SL38A	SL310A	
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	80	100	V
Maximum RMS voltage	$V_{RMS}$	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	$V_{DC}$	20	30	40	50	60	80	100	V
Maximum average forward rectified current at TL(see fig.1)	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	70							A
Maximum instantaneous forward voltage at 3.0A	$V_F$	0.45		0.50		0.70		V	
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	0.5 20.0				0.2 10.0		mA	
Typical junction capacitance (NOTE 1)	$C_J$	500			300			pF	
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	75.0							°C/W
Operating junction temperature range	$T_J$	-55 to +125					-55 to +150		°C
Operating storage temperature range	$T_{STG}$	-55 to +150							°C

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas.

**Ratings And Characteristic Curves**

FIG. 1- FORWARD CURRENT DERATING CURVE

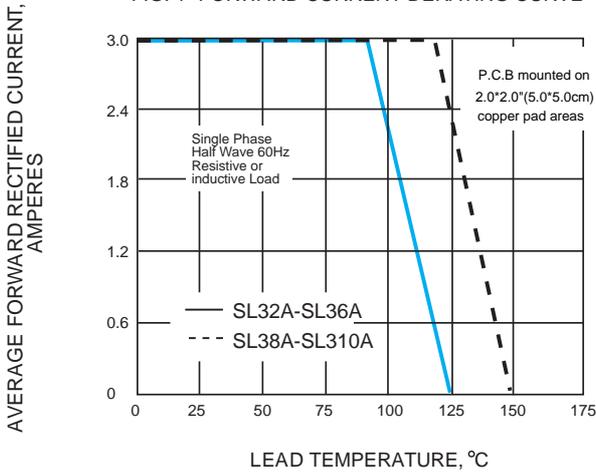


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

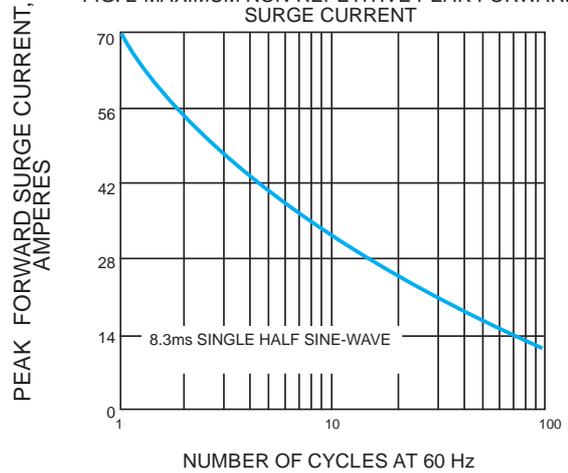


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

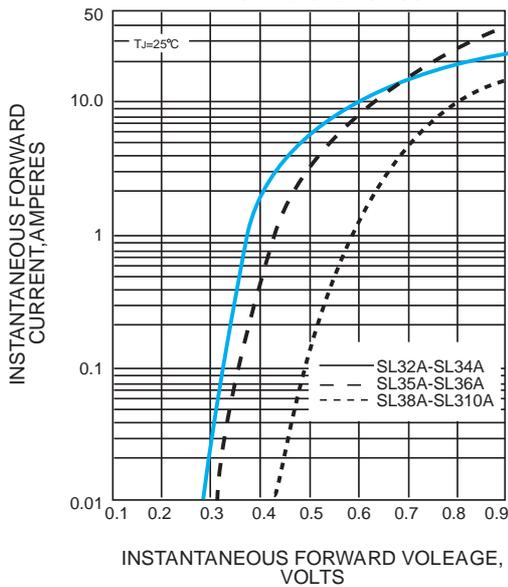


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

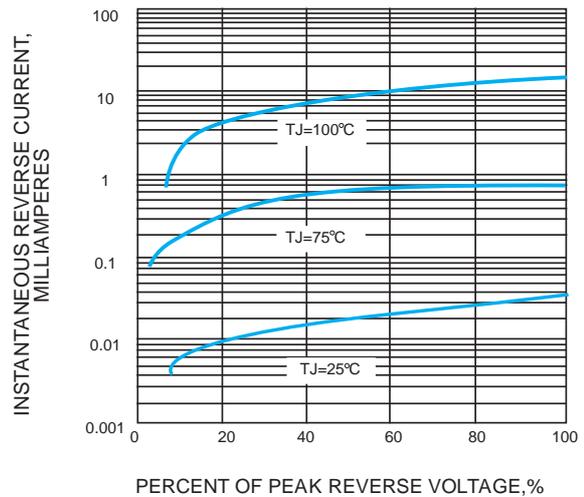


FIG. 5-TYPICAL JUNCTION CAPACITANCE

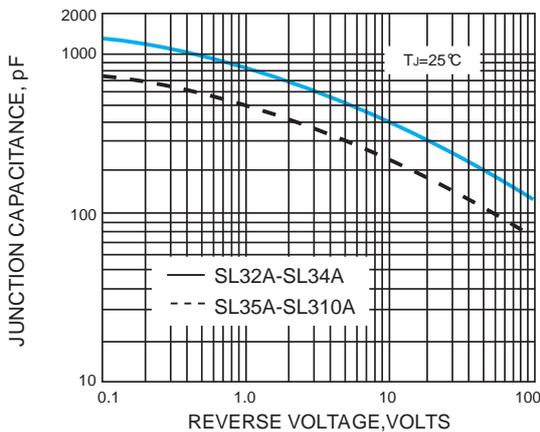
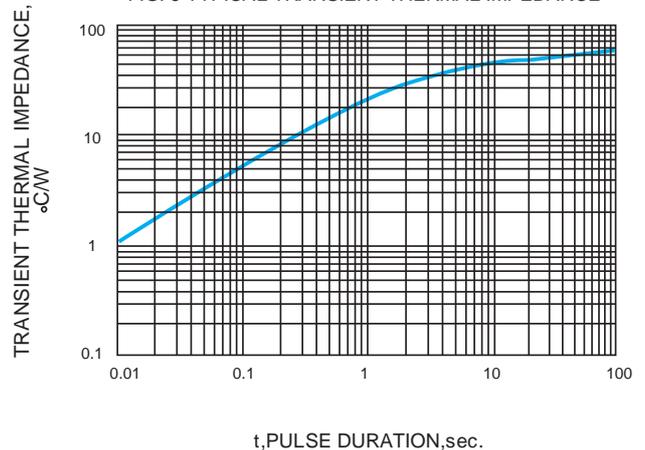
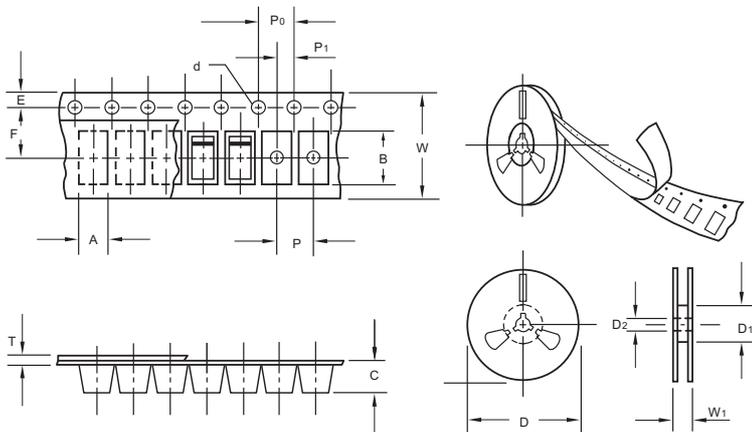


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



## Packing information



unit:mm

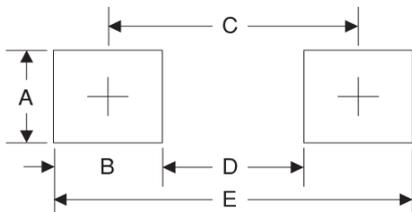
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D <sub>1</sub>	min	62.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W <sub>1</sub>	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	80,000	12.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215